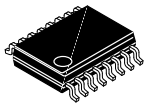
CM2006

Praetorian® L-C LCD and Camera EMI Filter Array with ESD Protection

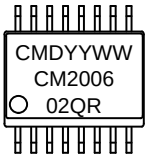
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QSOP16
QR SUFFIX
CASE 492

MARKING DIAGRAM



CM2006−02QR = Specific Device Code
YY = Year
WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping†
CM2006−02QR	QSOP−16 (Pb−Free)	2500/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

Product Description

The CM2006 connects between the VGA or DVI−I port connector and the internal analog or digital flat panel controller logic. The CM2006 incorporates ESD protection for all signals, level shifting for the DDC signals and buffering for the SYNC signals. ESD protection for the video, DDC and SYNC lines is implemented with low−capacitance current steering diodes.

All connector interface pins are designed to safely handle the high current spikes specified by IEC−61000−4−2 Level 4 (±8 kV contact discharge). The ESD protection for the DDC, SYNC and VIDEO signal pins is designed to prevent “backdrive current” when the device is powered down while connected to a video source that is powered up.

Separate positive supply rails are provided for the VIDEO / SYNC signals and DDC signals to facilitate interfacing with low voltage video controller ICs and microcontrollers to provide design flexibility in multi−supply−voltage environments.

Two Schmitt−triggered non−inverting buffers redrive and condition the HSYNC and VSYNC signals from the video connector (SYNC1, SYNC2). These buffers accept VESA VSIS compliant TTL input signals and convert them to CMOS output levels that swing between ground and V_{CC}.

Two N−channel MOSFETs provide the level shifting function required when the DDC controller or EDID EEPROM is operated at a lower supply voltage than the monitor. The gate terminals for these MOSFETS (V_{CC_DDC}) should be connected to the supply rail (typically 3.3 V, 2.5 V, etc.) that supplies power to the transceivers of the DDC controller.

Features

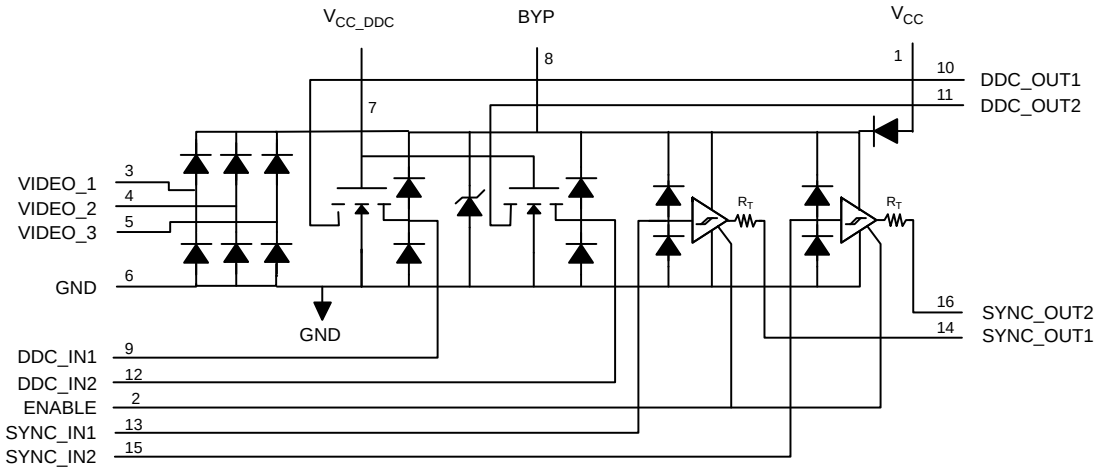
- Includes ESD Protection, Level−Shifting, Buffering and Sync Impedance Matching
- VESA VSIS Version 1 Revision 2 Compatible Interface
- Supports Optional NAVI Signalling Requirements
- 7 Channels of ESD Protection for all VGA Port Connector Pins. All Pins Meet IEC−61000−4−2 Level 4 ESD Requirements (±8 kV Contact Discharge)
- Very Low Loading Capacitance from ESD Protection Diodes on VIDEO Lines (3 pF Maximum)
- Schmitt−Triggered Input Buffers for HSYNC and VSYNC Lines
- These Devices are Pb−Free and are RoHS Compliant
- Bidirectional Level Shifting N−Channel FETs Provided for DDC_CLK & DDC_DATA Channels
- Backdrive Protection on all Lines
- Compact 16−Lead QSOP Package

Applications

- VGA and DVI−I Ports in:
  - Monitors
  - TVs

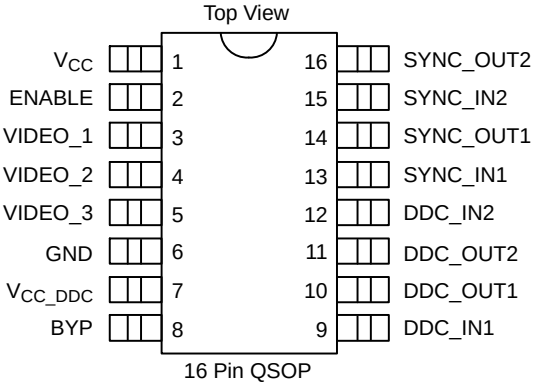
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ELECTRICAL SCHEMATIC



PACKAGE / PINOUT DIAGRAM

Top View



16 Pin QSOP

Table 1. PIN DESCRIPTIONS

Lead(s)	Name	Description
1	V_{CC}	This is a supply input for the SYNC_1 and SYNC_2 level shifters, video protection and the DDC circuits.
2	ENABLE	Active high enable. Disables the Sync buffer outputs when low.
3	VIDEO_1	Video signal ESD protection channel. This pin is typically tied one of the video lines between the controller device and the video connector.
4	VIDEO_2	Video signal ESD protection channel. This pin is typically tied one of the video lines between the controller device and the video connector.
5	VIDEO_3	Video signal ESD protection channel. This pin is typically tied one of the video lines between the controller device and the video connector.
6	GND	Ground reference supply pin.
7	V_{CC_DDC}	This is an isolated supply input for the DDC_1 and DDC_2 level−shifting N−FET gates.
8	BYP	An external 0.22 μF bypass capacitor is required on this pin.
9	DDC_IN1	DDC signal input. Connects to the video connector side of one of the DDC lines.signal output.
10	DDC_OUT1	DDC signal output. Connects to the monitor DDC logic.
11	DDC_OUT	DDC signal output. Connects to the monitor DDC logic.
12	DDC_IN2	DDC signal input. Connects to the video connector side of one of the DDC lines
13	SYNC_IN1	Sync signal buffer input. Connects to the video connector side of one of the sync lines.
14	SYNC_OUT1	Sync signal buffer output. Connects to the monitor SYNC logic.
15	SYNC_IN2	Sync signal buffer input. Connects to the video connector side of one of the sync lines.
16	SYNC_OUT2	Sync signal buffer output. Connects to the monitor SYNC logic.

SPECIFICATIONS

Table 2. ABSOLUTE MAXIMUM RATINGS

Parameter	Rating	Units
V_{CC_DDC} and V_{CC} Supply Voltage Inputs	[GND − 0.5] to +6.0	V
DC Voltage at Inputs VIDEO_1, VIDEO_2, VIDEO_3 DDC_IN1, DDC_IN2 DDC_OUT1, DDC_OUT2 SYNC_IN1, SYNC_IN2, ENABLE	 [GND − 0.5] to [V_{CC} + 0.5] [GND − 0.5] to 6.0 [GND − 0.5] to 6.0 [GND − 0.5] to [V_{CC} + 0.5]	V
Operating Temperature Range	−40 to +85	°C
Storage Temperature Range	−40 to +150	°C
Package Power Rating (T_A = 25°C)	500	mW

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 3. STANDARD OPERATING CONDITIONS

Parameter	Rating	Units
Operating Temperature Range	−40 to +85	°C
V_{CC}	5	V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

Table 4. ELECTRICAL OPERATING CHARACTERISTICS (Note 1)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
I_{CC_DDC}	V_{CC_DDC} Supply Current	V_{CC_DDC} = 5.0 V			10	μA
I_{CC}	V_{CC} Supply Current	V_{CC} = 5 V; SYNC inputs at GND or V_{CC}; SYNC outputs unloaded			1	mA
		V_{CC} = 5 V; SYNC inputs at 3.0 V; SYNC outputs unloaded			2.0	mA
V_F	ESD Diode Forward Voltage	I_F = 10 mA			1.0	V
V_{IH}	Logic High Input Voltage	V_{CC} = 5.0 V; (Note 2)	2.0			V
V_{IL}	Logic Low Input Voltage	V_{CC} = 5.0 V; (Note 2)			0.5	V
V_{HYS}	Hysteresis Voltage	V_{CC} = 5.0 V; (Note 2)		400		mV
V_{OH}	Logic High Output Voltage	I_{OH} = 0 mA, V_{CC} = 5.0 V; (Note 2)	4.0			V
V_{OL}	Logic Low Output Voltage	I_{OL} = 0 mA, V_{CC} = 5.0 V; (Note 2)			0.15	V
R_{OUT}	SYNC Driver Output Resistance	V_{CC} = 5.0 V; SYNC Inputs at GND or 3.0 V	7	15	24	Ω
I_{IN}	Input Current VIDEO Inputs	V_{CC} = 5.0 V; V_{IN} = V_{CC} or GND			±10	μA
	SYNC_IN1, SYNC_IN2 Inputs	V_{CC} = 5.0 V; V_{IN} = V_{CC} or GND			±10	μA
I_{OFF}	Level Shifting N−MOSFET “OFF” State Leakage Current	(V_{CC_DDC} − V_{DDC_IN}) < 0.4 V; V_{DDC_OUT} = V_{CC_DDC}			10	μA
		(V_{CC_DDC} − V_{DDC_OUT}) < 0.4 V; V_{DDC_IN} = V_{CC_DDC}			10	μA
$I_{BACKDRIVE}$	Current conducted from input pins when Vcc is powered down.	V_{CC} < V_{INPUT_PIN}; (Note 5)		10		μA
V_{ON}	Voltage Drop Across Level−shifting N−MOSFET when ”ON”	V_{CC_DDC} = 2.5 V; V_S = GND; I_{DS} = 3 mA			0.18	V
C_{IN_VID}	VIDEO Input Capacitance	V_{CC} = 5.0 V; V_{IN} = 2.5 V; f = 1 MHz			3	pF
		V_{CC} = 2.5 V; V_{IN} = 1.25 V; f = 1 MHz			3.5	pF
t_{PLH}	SYNC Driver L => H Propagation Delay	C_L = 50 pF; V_{CC} = 5.0 V; Input t_R and t_F < 5 ns			12	ns
t_{PHL}	SYNC Driver H => L Propagation Delay	C_L = 50 pF; V_{CC} = 5.0 V; Input t_R and t_F < 5 ns			12	ns
t_R, t_F	SYNC Driver Output Rise & Fall Times	C_L = 50 pF; V_{CC} = 5.0 V; Input t_R and t_F < 5 ns		3		ns
V_{ESD1}	ESD Withstand Voltage, Sync_out pins only	V_{CC} = 5 V; (Notes 3 and 4)	±2			kV
V_{ESD}	ESD Withstand Voltage	V_{CC} = 5 V; (Notes 3 and 5)	±8			kV

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. All parameters specified over standard operating conditions unless otherwise noted.
2. These parameters apply only to the SYNC drivers. Note that $R_{OUT} = R_T + R_{BUFFER}$.
3. Per the IEC−61000−4−2 International ESD Standard, Level 4 contact discharge method. BYP and V_{CC} must be bypassed to GND via a low impedance ground plane with a 0.22 μF, low inductance, chip ceramic capacitor at each supply pin. ESD pulse is applied between the applicable pins and GND. ESD pulses can be positive or negative with respect to GND. Applicable pins are: VIDEO_1, VIDEO_2, VIDEO_3, SYNC_IN1, SYNC_IN2, DDC_IN1 and DDC_IN2. All pins are ESD protected to the industry standard ±2 kV Human Body Model (MIL−STD−883, Method 3015).
4. This specification applies to the SYNC_OUT pins only.
5. Applicable pins are: VIDEO_1, VIDEO_2, VIDEO_3, SYNC_IN1, SYNC_IN2, DDC_IN1 and DDC_IN2.

APPLICATION INFORMATION

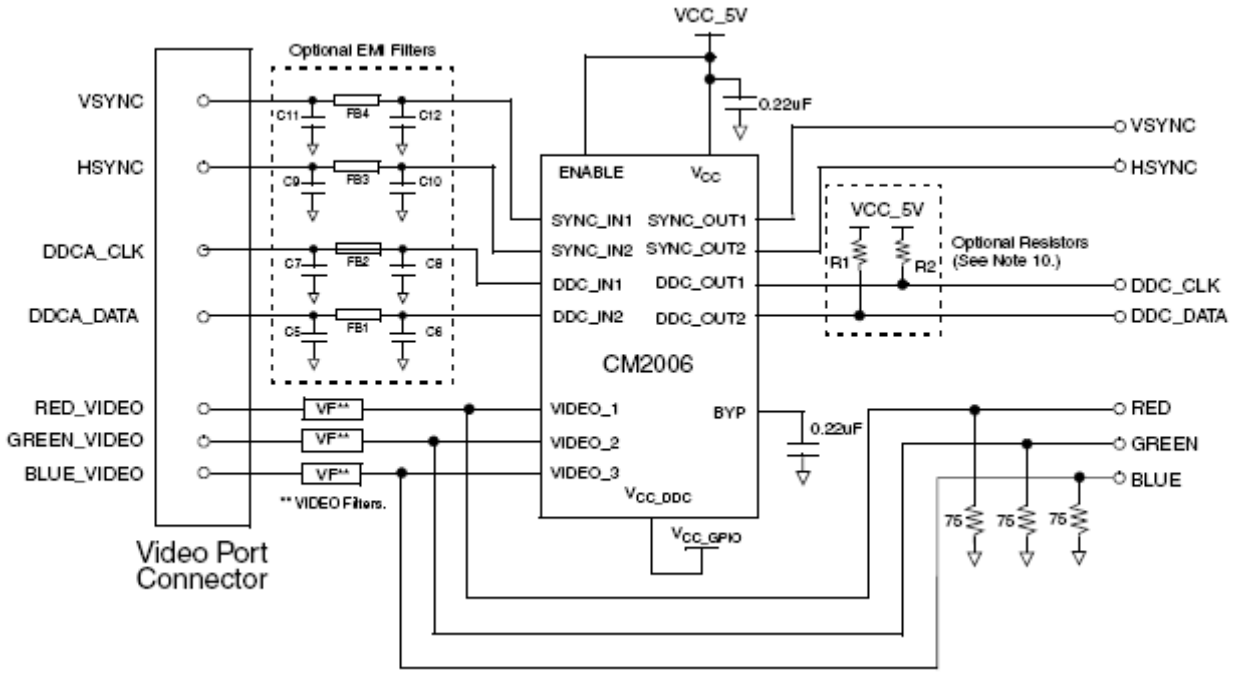


Figure 1. Typical Application Connection Diagram

NOTES:

1. The CM2006 should be placed as close to the VGA or DVI−I connector as possible.
2. The ESD protection channels VIDEO_1, VIDEO_2, VIDEO_3 may be used interchangeably between the R, G, B signals.
3. If differential video signal routing is used, the RED, BLUE, and GREEN signal lines should be terminated with external 37.5 Ω resistors.
4. “VF” are external video filters for the RGB signals.
5. Supply bypass capacitors C1 and C2 must be placed immediately adjacent to the corresponding Vcc pins. Connections to the Vcc pins and ground plane must be made with minimal length copper traces (preferably less than 5 mm) for best ESD protection.
6. The bypass capacitor for the BYP pin has been omitted in this diagram. This results in a reduction in the maximum ESD withstand voltage at the DDC_OUT pins from ±8 kV to ±2 kV. If 8 kV ESD protection is required, a 0.22 μF ceramic bypass capacitor should be connected between BYP and ground.
7. The SYNC buffers may be used interchangeably between HSYNC and VSYNC.
8. The EMI filters at the SYNC_OUT and DDC_OUT pins (C5 to C12, and Ferrite Beads FB1 to FB4) are for reference only. The component values and filter configuration may be changed to suit the application.
9. The DDC level shifters DDC_IN, DDC_OUT, may be used interchangeably between DDCA_CLK and DDCA_DATA.
10. R1, R2 are optional. They may be used, if required, to pull the DDC_CLK and DDC_DATA lines to VCC_5V when no VGA card is connected to the VGA monitor. If used, it should be noted that “back current” may flow between the DDC pins and VCC_5V via these resistors when VCC_5V is powered down.

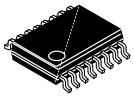
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MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

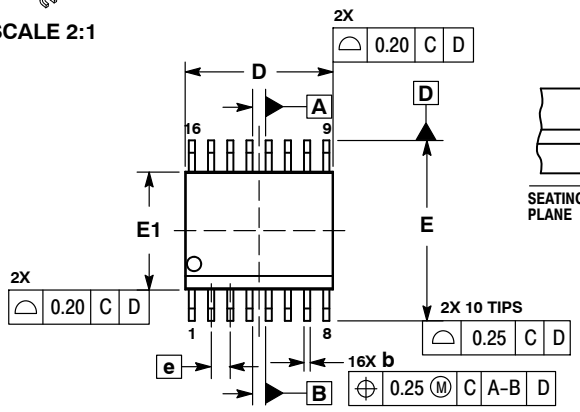
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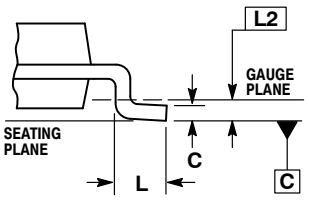
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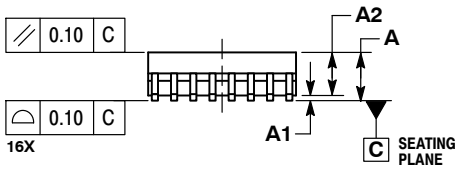


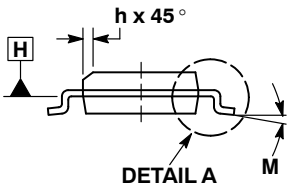
SCALE 2:1





DETAIL A

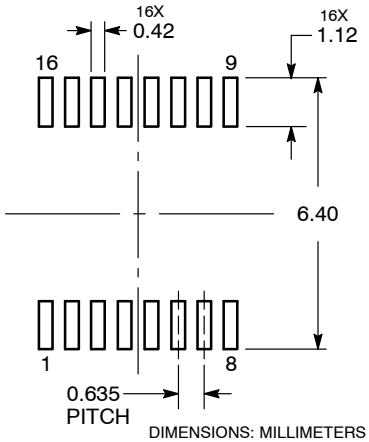




NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION.
4. DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.005 PER SIDE. DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.005 PER SIDE. D AND E1 ARE DETERMINED AT DATUM H.
5. DATUMS A AND B ARE DETERMINED AT DATUM H.

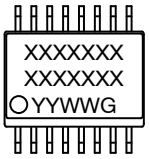
	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.053	0.069	1.35	1.75
A1	0.004	0.010	0.10	0.25
A2	0.049	----	1.24	----
b	0.008	0.012	0.20	0.30
c	0.007	0.010	0.19	0.25
D	0.193 BSC		4.89 BSC	
E	0.237 BSC		6.00 BSC	
E1	0.154 BSC		3.90 BSC	
e	0.025 BSC		0.635 BSC	
h	0.009	0.020	0.22	0.50
L	0.016	0.050	0.40	1.27
L2	0.010 BSC		0.25 BSC	
M	0 °	8 °	0 °	8 °

SOLDERING FOOTPRINT



DIMENSIONS: MILLIMETERS

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
YY = Year
WW = Work Week
G = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G”, may or not be present.

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